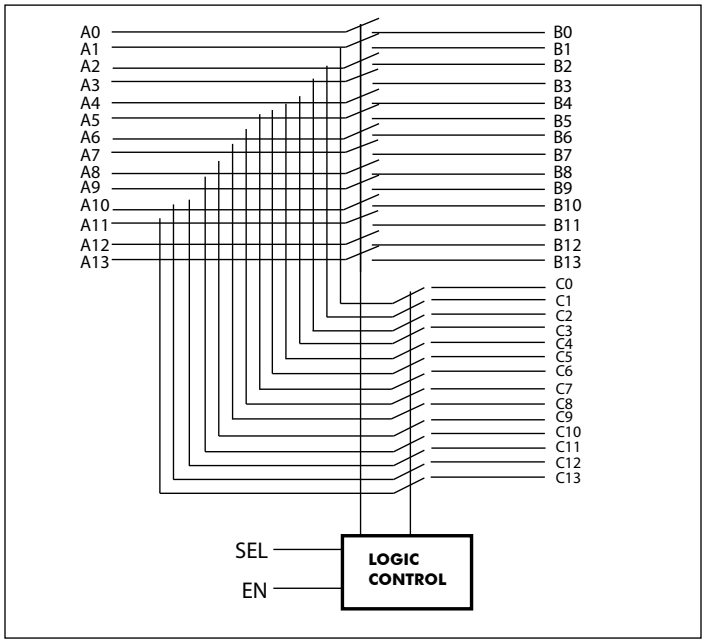
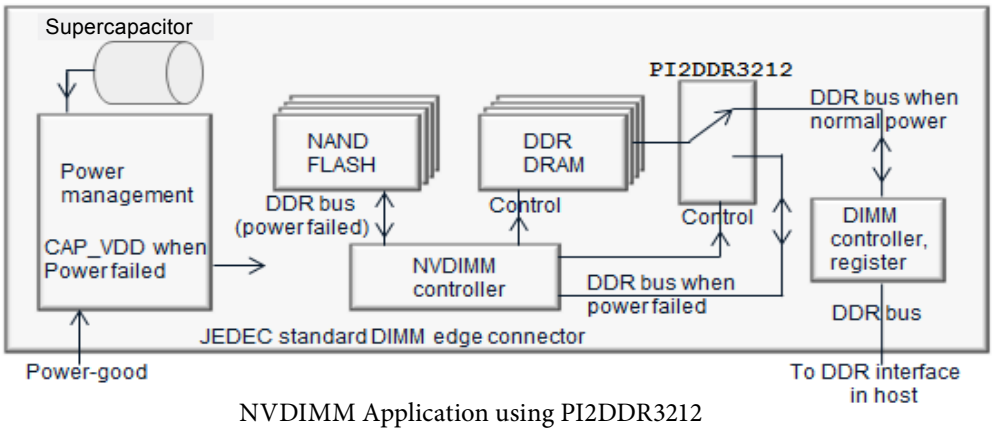
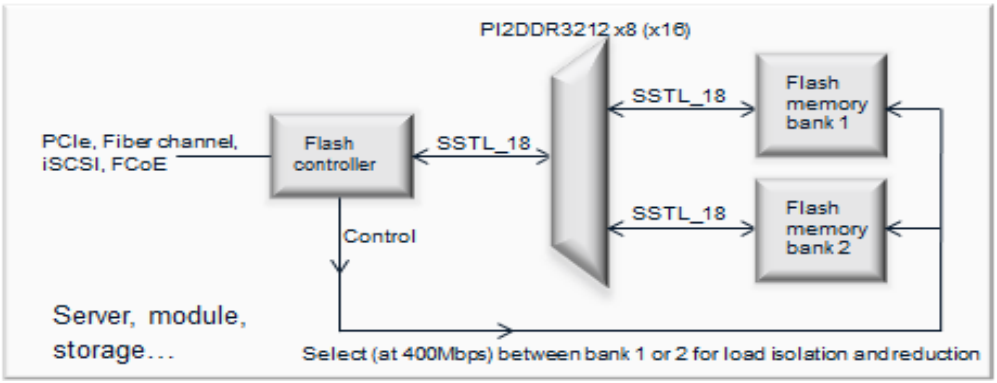
Block Diagram



Application



NVDIMM Application using PI2DDR3212



SSD, Flash storage application using PI2DDR3212

Pin Description

Pin Name	IO Type	Descriptions
V_{DD}	Power	1.35V, 1.5V or 1.8V power supply.
GND	Ground	1.35V, Ground connection
A[0:13]	I/O	14-bit wide input/output, port A
B[0:13]	I/O	14-bit wide input/output, port B
C[0:13]	I/O	14-bit wide input/output, port C
SEL	I	CMOS input for channel selection
EN	I	CMOS input When HIGH, connection is set using the SEL input signal When LOW, all ports are mutually isolated

Truth Table (SEL)

SEL	Function
0	Output B is selected
1	Output C is selected

Truth Table (EN)

EN	Function
1	Global Enable
0	Global Disable

Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Supply Voltage to Ground Potential ..... -0.3V to 2.5V
All Inputs..... -0.3V to V_{DD}+0.3V
Ambient Operating Temperature ..... -10 to +85°C
Storage Temperature..... -65 to +150°C
Junction Temperature ..... 150°C
Soldering Temperature..... 260°C

Note: Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended Operation Conditions

Parameter	Min.	Typ.	Max.	Unit
Ambient Operating Temperature	-10		+85	°C
Power Supply Voltage (measured in respect to GND)	+1.28	1.8	+2.0	V

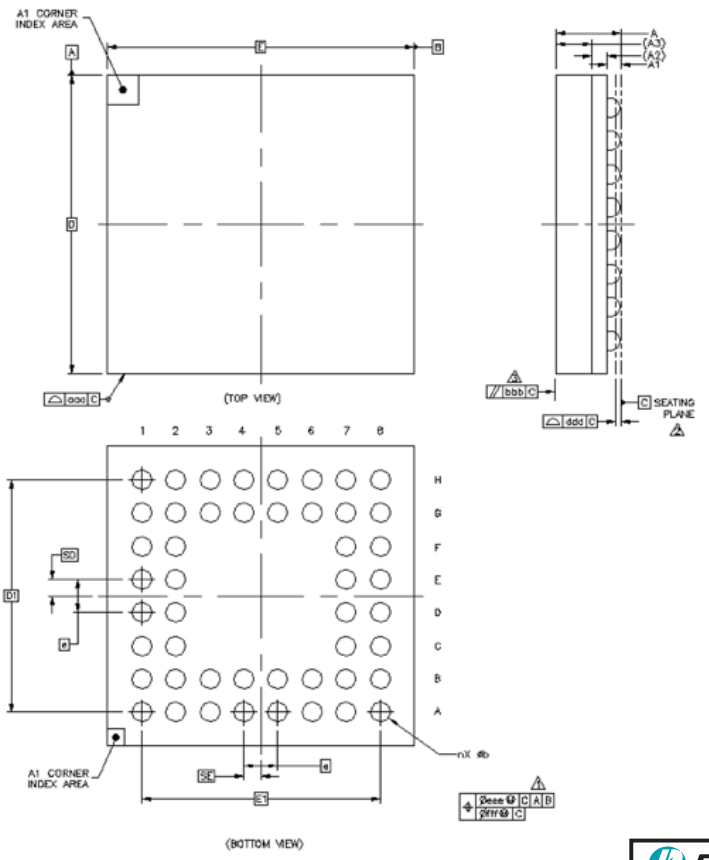
Static Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Supply Voltage		1.28	1.35/ 1.5 / 1.8	2	V
I_{DD}	V_{DD} Supply Current	EN= HIGH; V_{DD}=1.8V		220	350	µA
		EN= LOW; V_{DD}=1.8V		0.1	10	µA
I_{DD}	V_{DD} Supply Current	EN= HIGH; V_{DD}=1.35V		110	200	µA
		EN= LOW; V_{DD}=1.35V		0.05	2	µA
Control pin (SEL, EN)						
I_{IH}	High level digital input current	V_{IH}=V_{DD}, V_{DD}=2.0V			5	µA
I_{IL}	Low level digital input current	V_{IL} = GND, V_{DD}=2.0V			5	µA
V_{IH}	High level digital input voltage		0.8 *V_{DD}			V
V_{IL}	Low level digital input voltage				0.2*V_{DD}	V
I/O pin (A, B ,C)						
C_{OFF}	Switch OFF capacitance	f = 1MHz; $V_{I/O}$ = 0V		1.1		pF
C_{ON}	Switch ON capacitance	f = 1MHz; $V_{I/O}$ = 0V		2.1		pF

Dynamic Characteristics (over recommended operating conditions unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.(1)	Max.	Units
tstartup	Startup time	Supply voltage valid or EN going HIGH to channels specified characteristics		5	10	µs
trcfg	Reconfiguration time	SEL state change to channel specified operating characteristics		0.02	0.04	
tpd	Propagation delay	From A port to B port or C port or vice versa		60		ps
tsk	Skew time	From any output to any output		18	20	ps
V_I	Input Voltage		-0.3		Vdd+0.3	V
B	Bandwidth	-3dB intercept		3.3		GHz
C	Crosstalk attenuation	Adjacent channels are on; $0 \le f \le 1GHz$		-26		dB
I_L	Insertion Loss	$0 \le f \le 1GHz$		-0.7		dB
		f = 2.5GHz		-2.5		dB
R_L	Input Return Loss	$0 \le f \le 1GHz$		-23		dB
OI	Off Isolation	$0 \le f \le 1$ GHz		-28		dB

Packaging Mechanical: 48-Pin TFBGA



	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOR.	MAX.
TOTAL THICKNESS	A	---	---	1.1
STAND OFF	A1	0.16	---	0.26
SUBSTRATE THICKNESS	A2		0.21	REF
MOLD THICKNESS	A3		0.54	REF
BODY SIZE	D		4.5	BSC
	E		4.5	BSC
BALL DIAMETER			0.3	
BALL OPENING			0.275	
BALL WIDTH	b	0.27	---	0.37
BALL PITCH	e		0.5	BSC
BALL COUNT	n		48	
EDGE BALL CENTER TO CENTER	D1		3.5	BSC
	E1		3.5	BSC
BODY CENTER TO CONTACT BALL	SD		0.25	BSC
	SE		0.25	BSC
PACKAGE EDGE TOLERANCE	aaa		0.1	
MOLD FLATNESS	bbb		0.1	
COPLANARITY	ddd		0.08	
BALL OFFSET (PACKAGE)	eee		0.15	
BALL OFFSET (BALL)	fff		0.08	

PERICOM Enabling Serial Connectivity

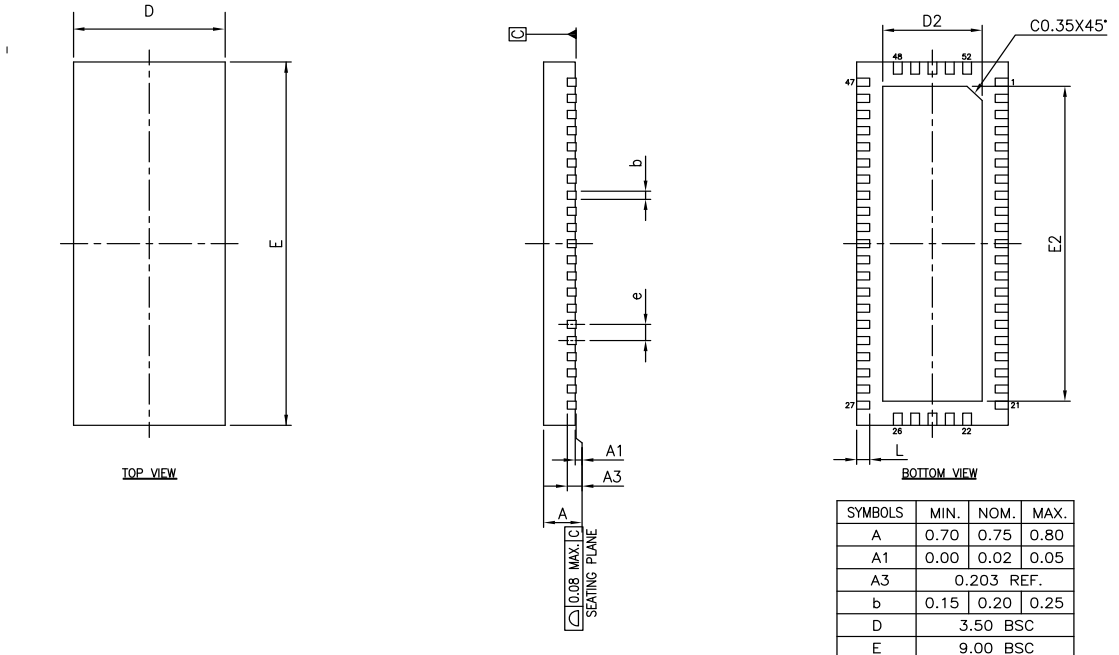
DATE: 07/21/11

DESCRIPTION: 48-pin, Thin Fine Pitch Ball Grid Array

PACKAGE CODE: NC (NC48)

DOCUMENT CONTROL #: PD-2103 REVISION: --

Packaging Mechanical: 52-Pin TQFN (ZL)



SYMBOLS	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3		0.203 REF.	
b	0.15	0.20	0.25
D		3.50 BSC	
E		9.00 BSC	
e		0.40 BSC	
L	0.20	0.30	0.40
D2	2.20	2.30	2.35
E2	7.70	7.80	7.85

Notes:
1. All dimensions are in millimeters.
2. Refer JEDEC MO-220
3. Bilateral coplanarity zone applies to the exposed heat sink slug aswell as the terminals.

PERICOM Enabling Serial Connectivity — **DATE: 07/15/11**

DESCRIPTION: 52-Pin, Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZL (ZL52)

DOCUMENT CONTROL #: PD-2102 **REVISION: --**

Ordering Information

Ordering Code	Packaging Code	Package Description
PI2DDR3212ZLE	ZL	52-Pin, Thin Quad Flat No-Lead (TQFN)
PI2DDR3212NCE	NC	48-Pin, Thin Fine Pitch Ball Grid Array (TFBGA)

NOTES:

1. Thermal characteristics can be found on the company web site at www.pericom.com/package

2. E = Pb-free and Green

3. Adding an X suffix = Tape/Reel